



The Fabrication of Compact and Porous Semiconductor Metal Oxide Layers

Guest Editor:

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Message from the Guest Editor

The fabrication of compact semiconductor metal oxide films tends to rely on techniques such as chemical or physical vapour deposition, atomic layer deposition, wet chemical methods (dip/spin/slot-die coating, electrochemical deposition, spray pyrolysis, ink-jet printing, etc.). Many of these have been successfully transferred from laboratories to manufacturing plants; however, there is still a great need for continuing the development of these routes to lower our global mass manufacturing carbon foot print and make advanced technologies available to a wider community. Porous semiconductor metal oxide layers, especially micro- and mesoporous materials, offer large specific surface areas, a key property for the successful development of efficient technologies in application fields.

In this issue, we aim to capture some of the latest advances in the development of environmentally friendly deposition methods and materials for the fabrication of semiconductor metal oxide compact and porous layers.





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